



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-07-15
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32C051F8P6	D0YA*44CXXXA	A	3068	2024-07-15
Amount	Unit of measure	Unit type	ST ECOPACK grade	
76	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
TSSOP	4.4x6.5	20	J bend	
Comment	Package : YA TSSOP 20 BODY 4.4 PITCH 0.65 0087225			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	D0YA*44CXXXA		75.6168		600000.0	100000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	3.907	mg	supplier	die	Silicon (Si)	7440-21-3		3.825	mg	979021	50581
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	999	52
				supplier	metallization	Copper (Cu)	7440-50-8		0.035	mg	8991	465
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.012	mg	2997	155
				supplier	Passivation	Silicon Nitride	12033-89-5		0.009	mg	2248	116
				supplier	Passivation	Silicon Oxide	7631-86-9		0.022	mg	5744	297
Leadframe (C7025 + NiPdAu)	M-011 Other inorganic materials	34.433	mg	supplier	alloy	Copper (Cu)	7440-50-8		32.410	mg	941248	428609
				supplier	alloy	Nickel (Ni)	7440-02-0		1.073	mg	31162	14190
				supplier	alloy	Silicon (Si)	7440-21-3		0.232	mg	6738	3068
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.054	mg	1568	714
				supplier	coating	Nickel (Ni)	7440-02-0		0.647	mg	18790	8556
				supplier	coating	Palladium (Pd)	7440-05-3		0.014	mg	407	185
Glue eoxy (8601S-25)	M-011 Other inorganic materials	1.102	mg	supplier	coating	Gold (Au)	7440-57-5		0.003	mg	87	40
				supplier	glue	Silver (Ag)	7440-22-4		0.968	mg	878000	12796
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.055	mg	50000	729
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.055	mg	50000	729
				supplier	glue	Acrylate polymer	87320-05-6		0.022	mg	20000	291
				supplier	glue	Epoxyhexyloxytrimethoxysilane	3388-04-3		0.001	mg	1000	15
Bonding wire (CuA)	M-011 Other inorganic materials	0.229	mg	supplier	glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1000	15
				supplier	bonding wire	Copper (Cu)	7440-50-8		0.227	mg	990000	2998
Encapsulation (EME-G700KC)	M-011 Other inorganic materials	35.675	mg	supplier	bonding wire	Others	Proprietary		0.002	mg	10000	30
				supplier	molding compound	Silica, vitreous	60676-86-0		30.992	mg	868745	409863
				supplier	molding compound	Epoxy Resin	85954-11-6		2.621	mg	73464	34659
				supplier	molding compound	Phenol Resin	26834-02-6		1.747	mg	48975	23106
				supplier	molding compound	Carbon black	1333-86-4		0.175	mg	4898	2311
Finishing (NiPdAu)	M-011 Other inorganic materials	0.271	mg	supplier	molding compound	Bismuth compound	7440-69-9		0.140	mg	3918	1848
				supplier	connection coating	Nickel (Ni)	7440-02-0		0.264	mg	974170	3491
				supplier	connection coating	Palladium (Pd)	7440-05-3		0.006	mg	22140	79
				supplier	connection coating	Gold (Au)	7440-57-5		0.001	mg	3690	13